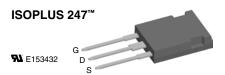


CoolMOS^{™ 1)} Power MOSFET in ISOPLUS247[™] Package

N-Channel Enhancement Mode Low R_{DSon}, High V_{DSS} MOSFET Package with Electrically Isolated Base $V_{DSS} = 800 V$ $R_{DS(on)} = 125 m\Omega$





G = Gate, D = Drain, S = Source

= 25 A

MOSFET				
Symbol	Conditions	Maximum Ratings		
V _{DSS}	$T_{VJ} = 25^{\circ}C$ to $150^{\circ}C$	800	V	
V _{GS}		± 20	V	
I _{D25}	$T_{c} = 25^{\circ}C$ $T_{c} = 90^{\circ}C$	25 18	A A	
dv/dt	$V_{DS} < V_{DSS}$; $I_F \le 17 \text{ A} \mid di_F/dt \mid \le 100 \text{ A/}\mu\text{s}$ $T_{VJ} = 150 ^{\circ}\text{C}$	6	V/ns	
E _{AS} E _{AR}	$I_D = 4 \text{ A}; L = 80 \text{ mH}; T_C = 25^{\circ}\text{C}$ $I_D = 17 \text{ A}; L = 3.3 \text{ mH}; T_C = 25^{\circ}\text{C}$	0.67 0.5	mJ mJ	

Symbol Conditions

Characteristic Values

 $(T_{VJ} = 25^{\circ}C, \text{ unless otherwise specified})$

		min.	typ.	max.	
R _{DSon}	$V_{GS} = 10 \text{ V}; I_D = I_{D90}$		125	150	mΩ
V _{GS(th)}	$V_{DS} = 20 \text{ V}; I_{D} = 2 \text{ mA}$	2		4	V
I _{DSS}	$V_{DS} = V_{DSS}; V_{GS} = 0 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$		100	50	μ Α μ Α
$I_{\rm GSS}$	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0 \text{ V}$			200	nA
Q _g Q _{gs} Q _{gd}			180 24 92	355	nC nC nC
t _{d(on)} t _r t _{d(off)} t _f	$\begin{cases} V_{GS} = 10 \text{ V}; V_{DS} = 640 \text{ V} \\ I_{D} = 34 \text{ A}; R_{G} = 2.2 \Omega \end{cases}$		25 15 72 6		ns ns ns ns
V _F	(reverse conduction) $I_F = 12.5 \text{ A}$; $V_{GS} = 0 \text{ V}$		1	1.3	V
R _{thJC}				0.5	K/W

Features

- ISOPLUS247[™] package with DCB Base
- Electrical isolation towards the heatsink
- Low coupling capacitance to the heatsink for reduced EMI
- High power dissipation
- High temperature cycling capability of chip on DCB
- JEDEC TO-247AD compatible
- Easy clip assembly
- fast CoolMOS^{™ 1)} power MOSFET 3rd generation
- High blocking capability
- Low on resistance
- Avalanche rated for unclamped inductive switching (UIS)
- Low thermal resistance due to reduced chip thickness
- Enhanced total power density

Applications

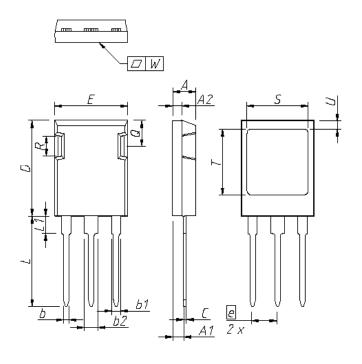
- Switched mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)
- Power factor correction (PFC)
- Welding
- Inductive heating

¹⁾CoolMOS[™] is a trademark of Infineon Technologies AG.



Component					
Symbol	Conditions	Maximum Ratings			
V_{ISOL}	$I_{ISOL} \le 1$ mA; 50/60 Hz	2500	V~		
T _{VJ}		-40+150	°C		
T _{stg}		-40+125	°C		
T _L	1.6 mm from case for 10 s	300	°C		
F _c	mounting force with clip	20 120	N		

Symbol	Conditions	Characteristic Values			
		min.	typ.	max.	
C _P	coupling capacity bewtween shorted pin and mounting tab in the case		30		pF
R _{thCH}	with heatsink compound		0.25		K/W
Weight			6		g



DIM.	MILLII	MILLIMETER		INCHE\$		
Dirt.	MIN	MAX	MIN	MAX		
Α	4,83	5,21	0,190	0,205		
A1	2,29	2,54	0,090	0,100		
A2	1,91	2,16	0,075	0,085		
b	1,14	1,40	0,045	0,055		
<i>b1</i>	1,91	2,15	0,075	0,085		
b2	2,92	3,20	0,115	0,126		
(0,61	0,83	0,024	0,033		
D	20,80	21,34	0,819	0,840		
E	15, 75	16, 13	0,620	0,635		
е	5,45 BSC		0,215 BSC			
L	19,81	20,60	0,780	0,811		
L1	3,81	4, <i>38</i>	0,150	0,172		
a	5,59	6,20	0,220	0,244		
R	4,32	4,85	0,170	0,191		
\$	13,21	13,72	0,520	0,540		
T	15, 75	16,26	0,620	0,640		
U	1,65	2,03	0,065	0,080		
W	_	0,10	-	0,004		
Die kanveye Formidee Substratee jet für z 0.04 mm über der Kunstetafff						

Die konvexe Form des Substrates ist typ. < 0.04 mm über der Kunststofff-oberfläche der Bauteilunterseite

The convex bow of substrate is typ. < 0.04 mm over plastic surface level of

Die Gehäuseabmessungen entsprechen demTyp TO-247 AD gemäß JEDEC außer Schraubloch und L_{max}.
This drawing will meet all dimensions requiarement of JEDEC outline TO-247 AD except screw hole and except L_{max}.

